

# 2012 EDITORIAL CALENDAR

## January

- Test and Measurement
- Cables and Connectors
- Wireless ICs and Modules

**Products:** Test Equipment, EDA, Cables and Connectors

**Bonus Distribution:** DesignCon, Jan 30-31

## April

- Passive Components
- Cables and Connectors
- Field Test

**Products:** RFICs, MMICs, Field Test, Couplers and Hybrids

**Bonus Distribution:** CTIA, May 8-10

## July

- High Power
- Cables and Connectors
- Sensors

**Products:** Telecom, Filters, EMC Products

**Bonus Distribution:** IEEE EMC Symposium, Aug 5-9

## October

- Aerospace
- Cables and Connectors
- ICs & Devices

**Products:** Design Software, Space Products, Amplifiers

## February

- ICs and Devices
- Power Amps
- MCMs, SoCs, SIPs

**Products:** Resistive Products, Oscillators, Synthesizers

**Bonus Distribution:** Satellite 2012, Mar 12-15

## May

- Signal Generation
- MM-Wave
- IMS Preview

**Products:** 3G, 4G, Substrates and Laminates, Power Products

**Bonus Distribution:** MTT IMS, June 17-22

## August

- High Speed Digital
- VCOs & Synthesizers
- Wireless ICs

**Products:** Switches, Synthesizers, EDA, Power Amps

**Bonus Distribution:** AOC International, Sept 23-26

## November

- Microwave and Power Modules
- MM-Wave
- Signal Generation

**Products:** MM-Wave, Passives, Test and Measurement

**Bonus Distribution:** Asia Pacific Microwave Conference, Dec 4-7

## March

- Defense and Homeland Security
- Mixers/Modulators
- EDA

**Products:** MW Components, Amplifiers, Switches

**Bonus Distribution:** WAMICON, April 16-17

## June

- Radar and Avionics
- Antennas
- EMI/EMC

**Products:** Antennas, Front-End Components, Defense/Homeland Security

**Bonus Distribution:** AP/URSI, July 8-14

## September

- Government and Military Electronics
- Simulation and Layout Software
- COTS Components

**Products:** Modules, ICs, Filters

**Bonus Distribution:** EuMW Week, Oct 29-Nov 2  
MILCOM, Oct 29-Nov 1

## December

- Communications
- Mixers and Amps
- Subsystems and Systems – Power

**Products:** RFICs & MMICs, Signal Generation, Software

**Bonus Distribution:** Radio Wireless Week, Jan 15-18

## Editorial Submissions

### Regular Columns

Meetings & Events, In the News, Design Notes, High Frequency Applications

### Press Releases

Press releases for our informational columns should be sent by the first of the month prior to the desired publication date (e.g., April 1 for the May issue). Late-breaking news can be accommodated, but please advise the editors of urgent items by telephone or e-mail.

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### Article Contributions

We encourage the submission of technical articles, application notes and other editorial contributions. These may be on the topics noted above, or any other subject of current interest. Contact us with article ideas:

[editor@highfrequencyelectronics.com](mailto:editor@highfrequencyelectronics.com)

### How to Contact Us

Send press releases and other communications to our general editorial e-mail address:

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Additional technical articles can be published in each issue, covering other topics

**AD CLOSING DATES:** 15th of the prior month (next business day if weekend)

**AD MATERIAL DEADLINE:** 5 business days after ad closing

Contact your advertising sales representative for extra time or special requirements

**BONUS DISTRIBUTIONS:** Subject to change.